

# MicroStar BGA Discontinued and Redesigned



*Clock and Timing Solutions*

## ABSTRACT

This document should be used in conjunction with the device data sheet and describes the updated package designator for the indicated devices.

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# 1 Package Redesign Details

## Explanation

The devices in the MicroStar BGA™ packaging were redesigned using a laminate nFBGA package. The nFBGA package offers data sheet-equivalent electrical performance and data sheet-equivalent or better thermal performance. It provides the same X and Y dimensions as MicroStar BGA, and provides pin-to-pin and footprint compatibility. The nFBGA PCB land pattern and stencil recommendations have been updated to achieve better soldering results after extensive testing and evaluation. For more details, please refer to this [nFBGA Package Application Report](#).

When referencing the device data sheet, use the new package designator in place of the discontinued package designator throughout the document.

The orderable addendum at the end of the device data sheet will reflect the new package designator.

See the following page or the end of the device data sheet for the updated nFBGA package drawing.

**Table 1-1. Package Designator**

Old Package Designator	New Package Designator
ZQL	NMK
ZKE	NMJ

## Reason for Discontinuance

Due to an equipment End-Of-Life notice from our substrate supplier, we are phasing out certain MicroStar BGA and MicroStar Junior™ BGA packaging devices and offering a Last Time Buy.

These devices have now been converted to an nFBGA package.

## Devices Affected

The following table describes the devices affected, the old and new package designators, and references to the device data sheet.

**Table 1-2. Devices and Nomenclature**

Device	Discontinued MicroStar BGA Device	Redesigned Laminate nFBGA Device	Device Data Sheet
CDCU877A	CDCU877AZQLR	CDCU877ANMKR	SCAS688D
CDCU877A	CDCU877AZQLT	CDCU877ANMKT	SCAS688D
CDCUA877	CDCUA877ZQLR	CDCUA877NMKR	SCAS769A
CDCUA877	CDCUA877ZQLT	CDCUA877NMKT	SCAS769A
CDCU2A877	CDCU2A877ZQLR	CDCU2A877NMKR	SCAS827A
CDCU2A877	CDCU2A877ZQLT	CDCU2A877NMKT	SCAS827A
SN74SSTU32864	SN74SSTU32864ZKER	SN74SSTU32864NMJR	SCES434
SN74SSTUB32864	SN74SSTUB32864ZKER	SN74SSTUB32864NMJR	SCAS791A
SN74SSTUB32866	SN74SSTUB32866ZKER	SN74SSTUB32866NMJR	SCAS792C

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